

Resin Coated Copper Foil

FCL-TRL

This Resin Coated Copper Foil is designed to improve the overall cosmetic and functional properties of the external circuitry. A thin, high TG resin film acts as additional dielectric spacer and helps for an easier handling of thin foils without carrier. A significant reduction of the top waviness on typical glass fabric styles is achieved allowing a better photo definition of the external circuitry.

Copper Foil types:

- Very Low profile foil with HTE characteristics
- Low profile foil HTE characteristics
- Ultra-thin foils with a copper carrier

Copper Foil Thickness:

- Carrier supported (either 1oz or 2oz copper carrier): 3/35 μ m 5/35 μ m 5/70 μ m
- Unsupported copper foils: 12 μ m 18 μ m 35 μ m 70 μ m

High coating precision:

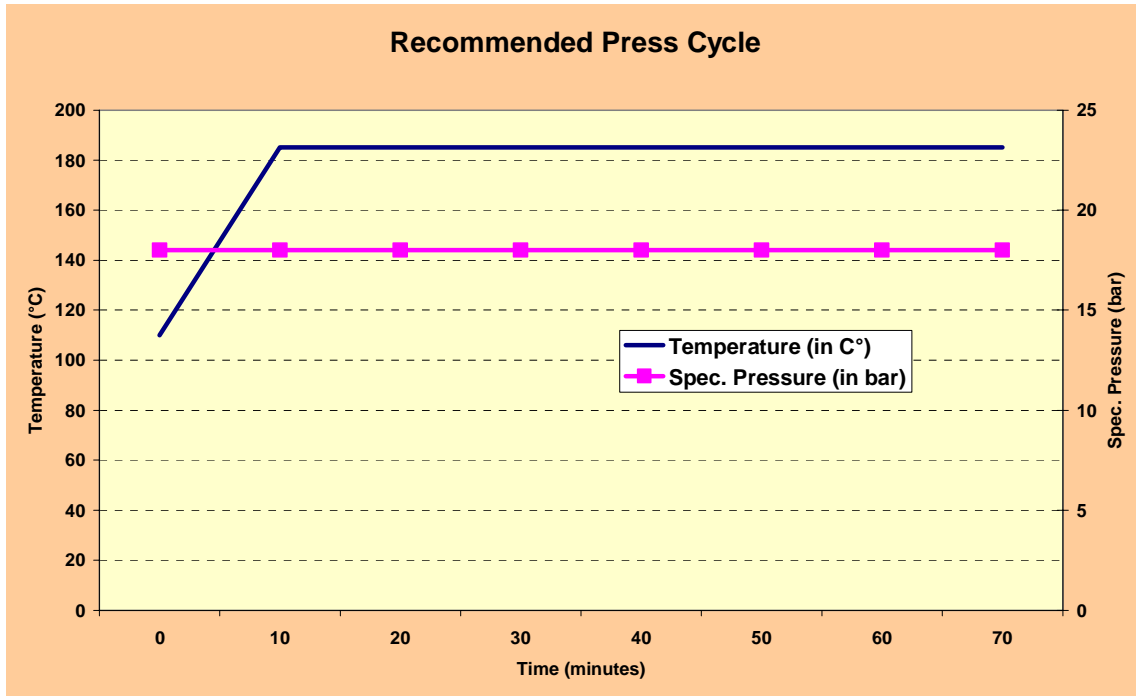
- Less than 2.5 μ m variation over roll length and width

Typical average properties:

Parameter	Units	Value	Condition
Resin thickness variation	μ m	< 2 μ	On 100% copper
Glass Transition Temperature TG (per DMA)	$^{\circ}$ C	>170	Onset
	$^{\circ}$ C	>180	Middle Point
Gel time	Sec	< 20	
Copper Peel Strength: on FR4 12 μ m & 18 μ m 12 μ m & 18 μ m 5 μ m/35 (*) (*) after galvanic build- up to 35 μ	N/mm	> 1.2	10" at 288 $^{\circ}$ C
	N/mm	>1.0	at 125 $^{\circ}$ C
	N/mm	>1.4	10" at 288 $^{\circ}$ C
Dielectric Constant ϵ_r		3.53	@ 10 MHz
		3.30	@ 1 GHz
Dissipation Factor tan δ		0.024	@ 10 MHz
		0.019	@ 1 GHz
Surface resistance	M Ω	1.4 E+07	35 $^{\circ}$ C/93% r.H.
	M Ω	7.8 E+09	125 $^{\circ}$ C
Volume resistivity	M Ω * cm	1.0 E+08	35 $^{\circ}$ C/93% r.H.
	M Ω * cm	3.5 E+09	125 $^{\circ}$ C

Recommended Press Cycle:

Use a conventional vacuum press: vacuum at once



Typical Temperature Profile:

Start from 110°C to 185°C in 10 minutes:
7.5°C/minute
Hold for 70 minutes
Cool down under pressure

Typical Pressure Profile:

15-20 bar for 90 minutes
Keep pressure during cooling

Recommended Storage Conditions:

Temperature: max. 25°C
Rel. humidity: between 40 - 60 %
Shelf life: max. 90 days

Availability:

FCL-TRL foil is available in rolls or in sheets with or without punched registration holes.

For further information, please contact: